

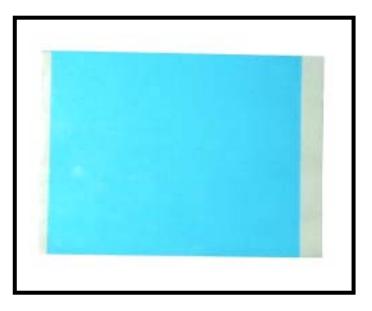
Thermal Management Materials, 6018 Material

Product Summary

MAJR 6000 Series thermal Management materials consist of sheet, adhesive, grease compounds and tape; these thermal materials are used in a wide variety of markets such as LED, chip sets for IC controller packages, IT for industrial and personal computers, DRAM Modules, telecom devices, automotive control units, and many other products for military and commercial markets.

Product Application (6018)

This family of thermally conductive tapes exhibit excellent adhesion capabilities at 1.1 to 1.4 kg/inch with a thermal conductivity of 1.0W/m-k. In addition. these materials exhibits а continuous use temperature of -20 to 120 deg. C. they are excellent for applications such as: heat sink onto graphic /drive processor or heat spreader onto power converter PCB, and LED lighting. The material can be supplied in sheet, roll form, and die-cut parts to your specification. Standard thickness is: 0.1mm, 0.15mm, 0.2mm, 0.25mm, 0.3mm. Max. width is 1030mm.



Physical	T1	T2	Т3	Τ4	Τ5
Reinforced Material	Fiberglass	Fiberglass	Fiberglass	Fiberglass	Fiberglass
Thickness	0.1mm	0.15mm	0.2mm	0.25mm	0.3mm
Peel Strength (PSTC-101)(N/25mm)	>13.72	>13.72	>13.72	>13.72	>13.72
Temp Resistance(S) °C (°F)	180 (356)	180 (356)	180 (356)	180 (356)	180 (356)
Temp Resistance(L) °C (°F)	120 (248)	120 (248)	120 (248)	120 (248)	120 (248)
Continues Use. Temp. (°C)	-20 to 120				

Product Technical Data (6018)

Technical Data (6018) continued

Adhesion

Retention (1Kg/Inch/25°C)	>48	>48	>48	>48	>48
Adhesion(Kg/Inch)	1.1	1.4	1.4	1.4	1.4
Initial Bonding Strength(Kg/Inch)	0.6	1.3	1.3	1.3	1.3

Electrical

Breakdown Voltage	2	2.5	3.5	4	6
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Thermal

Thermal conductivity (ASTM D5470)	1.0W/M.K	1.0W/M.K	1.0W/M.K	1.0W/M.K	1.0W/M.K
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Shelf life: 15 months at a maximum storage temperature of 28 deg. C, relative humidity of 60%.